MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Brodnet data speet

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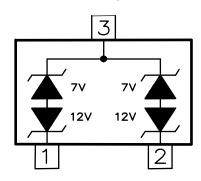




FEATURES

- 400 watts peak pulse power ($t_p = 8/20\mu s$)
- Transient protection for asymmetrical data lines to IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact) IEC 61000-4-4 (EFT) 40A (5/50ns) IEC 61000-4-5 (Lightning) 12A (8/20µs)
- Protects two +12V to -7V lines
- Low capacitance
- Low clamping voltage
- Solid-state silicon avalanche technology

Pin Configuration



APPLICATIONS

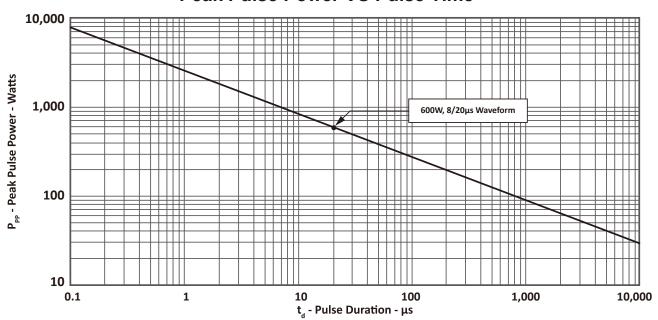
- Protection of RS-485 transceivers with extended common-mode range
- Security systems
- Automatic Teller Machines
- HFC systems
- Networks

Absolute Maximum Rating (Tamb=25°C unless otherwise specified)					
Rating	Symbol	Value	Units		
Peak Pulse Power (tp = 8/20µs)	P _{pk}	260	Watts		
Peak Pulse Current (tp = 8/20µs)	I _{PP}	10	А		
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V _{ESD}	15 8	kV		
Lead Soldering Temperature	TL	260 (10 sec.)	$^{\circ}$		
Operating Temperature	TJ	-55 to +125	$^{\circ}$		
Storage Temperature	T _{STG}	-55 to +150	$^{\circ}$		



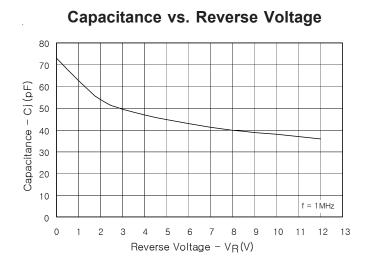
Electrical Characteristics(Tamb=25 °C)									
			Pins 1 to 3 and 2 to 3 (12V TVS)		Pins 3 to 1 and 3 to 2 (7V TVS)				
Parameter	Symbol	Conditions	MIN	TYP	МАХ	MIN	TYP	MAX	Units
Reverse Stand-Off Voltage	V _{RWM}	Pin 3 to 1 or Pin 2 to 1			12			7	V
Reverse Breakdown Voltage	V _{BR}	I _{PT} = 1mA	13.3			7.5			V
Reverse Leakage Current	I _R	$V_{R} = V_{RWM}$			1			20	μA
Clamping Voltage	V _c	$I_{pp} = 5A,$ tp = 8/20µs			20			10	V
Clamping Voltage	V _c	$I_{pp} = 10A,$ tp = 8/20µs			26			12	V
Junction Capacitance	C _j	V _R = OV, f = 1MHz			75			75	pF
		$V_R = V_{RWM}$, $f = 1MHz$		45			45		pF

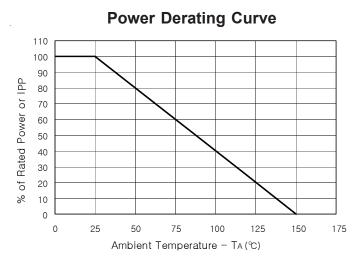
Peak Pulse Power VS Pulse Time





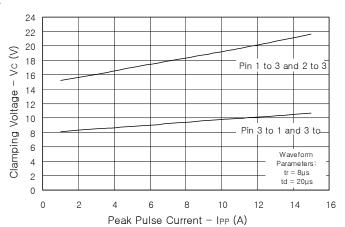
Electrical Characteristics Curve





Pulse Waveform 110 Waveform 100 Parameters: tr = 8μs td = 20μs 90 80 70 Percent of Ipp 60 50 40 $td = I_{PP}/2$ 20 10 0 0 10 15 30 25 Time (µs)

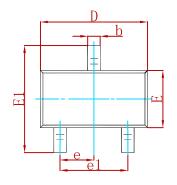
Clamping Voltage vs. Peak Pulse Current

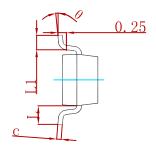


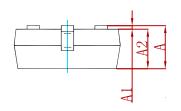




PACKAGE MECHANICAL DATA

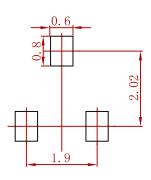






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950) TYP	0.03	7 TYP	
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

Suggested Pad Layout



- 1.Controlling dimension:in millimeters.2.General tolerance:± 0.05mm.3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESDBW712C2-MS	SOT-23	3000

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